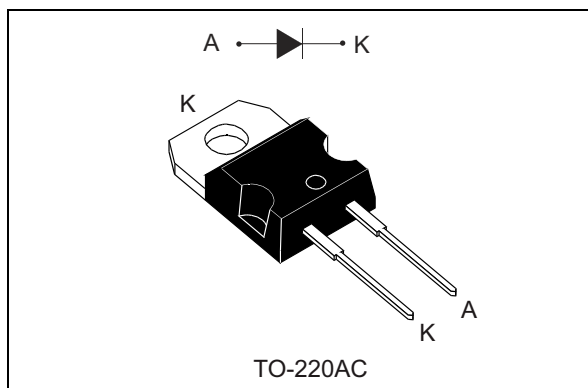


650 V power Schottky silicon carbide diode

Datasheet - production data



Features

- No or negligible reverse recovery
- Switching behavior independent of temperature
- Dedicated to PFC applications
- High forward surge capability

Description

The SiC diode is an ultrahigh performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide band gap material allows the design of a Schottky diode structure with a 650 V rating. Due to the Schottky construction, no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

Especially suited for use in PFC applications, this ST SiC diode will boost the performance in hard switching conditions. Its high forward surge capability ensures a good robustness during transient phases.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	12 A
V_{RRM}	650 V
$T_j (max)$	175 °C

1 Characteristics

Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		650	V
$I_{F(RMS)}$	Forward rms current		22	A
$I_{F(AV)}$	Average forward current	$T_c = 130\text{ °C}^{(1)}$, $\delta = 0.5$	12	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal, $T_c = 25\text{ °C}$	100	A
		$t_p = 10\text{ ms}$ sinusoidal, $T_c = 125\text{ °C}$	90	
		$t_p = 10\text{ }\mu\text{s}$ square, $T_c = 25\text{ °C}$	400	
I_{FRM}	Repetitive peak forward current	$T_c = 130\text{ °C}^{(1)}$, $T_j = 150\text{ °C}$, $\delta = 0.1$	50	A
T_{stg}	Storage temperature range		-55 to +175	°C
T_j	Operating junction temperature ⁽²⁾		-40 to +175	°C

1. Value based on $R_{th(j-c)}$ max.

2. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value		Unit
		Typ.	Max.	
$R_{th(j-c)}$	Junction to case	1.00	1.4	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	10	μA
		$T_j = 150\text{ °C}$		-	100	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 12\text{ A}$	-	1.56	V
		$T_j = 150\text{ °C}$		-	1.98	

1. $t_p = 10\text{ ms}$, $\delta < 2\%$

2. $t_p = 500\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.35 \times I_{F(AV)} + 0.096 \times I_{F(RMS)}^2$$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Test conditions	Typ.	Unit
$Q_{cj}^{(1)}$	Total capacitive charge	$V_R = 400\text{ V}$,	36	nC
C_j	Total capacitance	$V_R = 0\text{ V}$, $T_c = 25\text{ °C}$, $F = 1\text{ MHz}$	600	pF
		$V_R = 400\text{ V}$, $T_c = 25\text{ °C}$, $F = 1\text{ MHz}$	60	

1. Most accurate value for the capacitive charge: $Q_{cj} = \int_0^{V_{OUT}} C_j(V_R) \cdot dV_R$

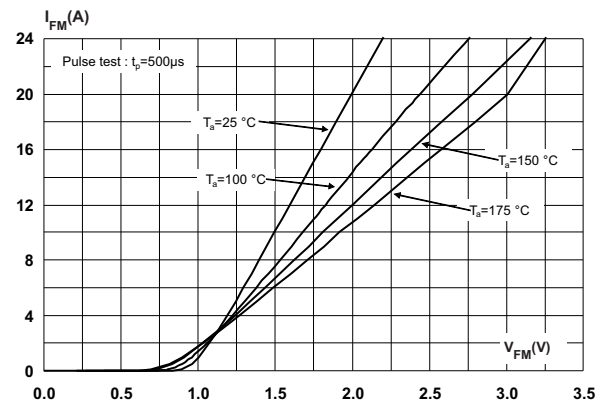
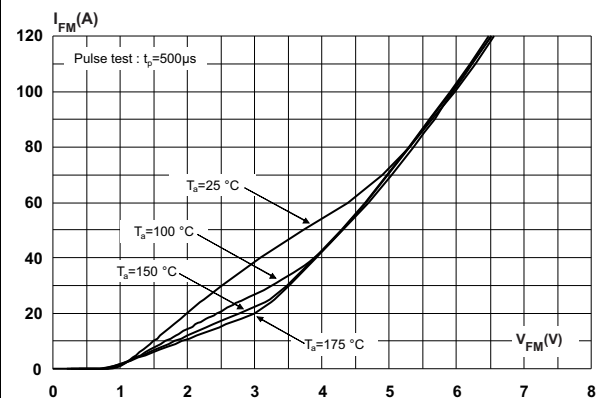
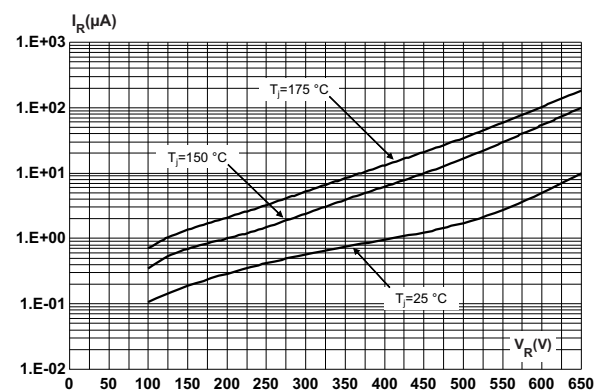
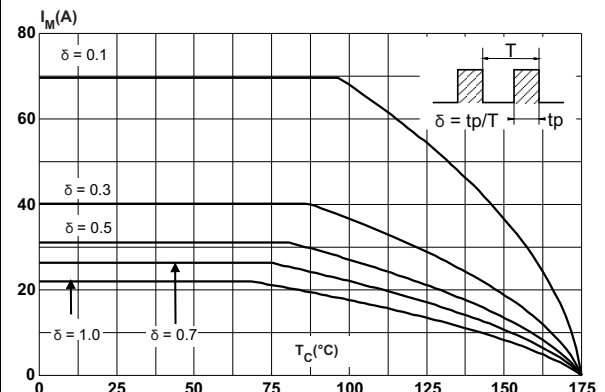
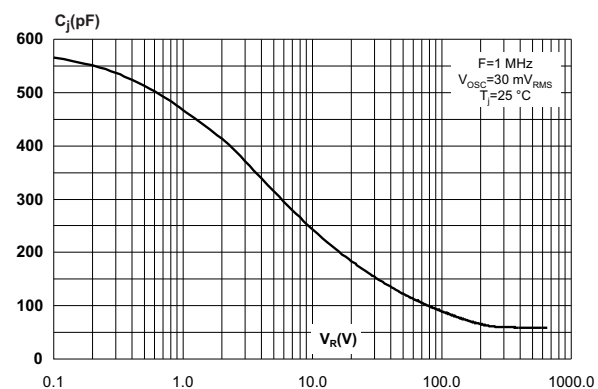
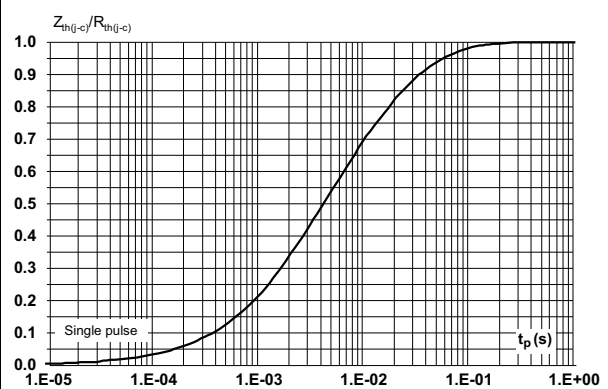
Figure 1. Forward voltage drop versus forward current (typical values, low level)**Figure 2. Forward voltage drop versus forward current (typical values, high level)****Figure 3. Reverse leakage current versus reverse voltage applied (typical values)****Figure 4. Peak forward current versus case temperature****Figure 5. Junction capacitance versus reverse voltage applied (typical values)****Figure 6. Relative variation of thermal impedance junction to case versus pulse duration**

Figure 7. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)

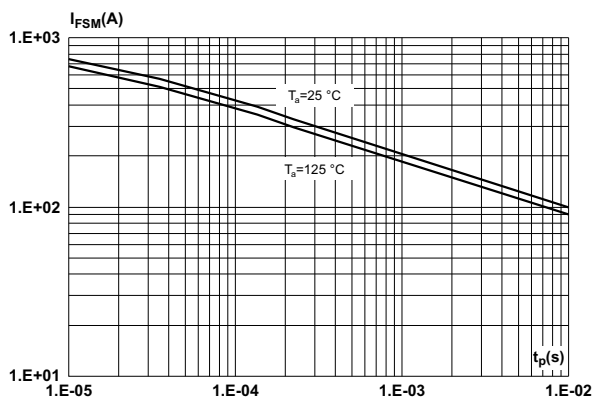
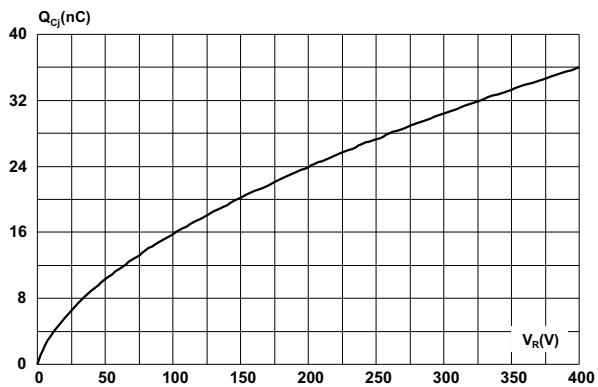


Figure 8. Total capacitive charges versus reverse voltage applied (typical values)



2 Package information

- Epoxy meets UL94, V0
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.7 N·m
- Cooling method: conduction (C)

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2.1 TO-220AC package information

Figure 9. TO-220AC package outline

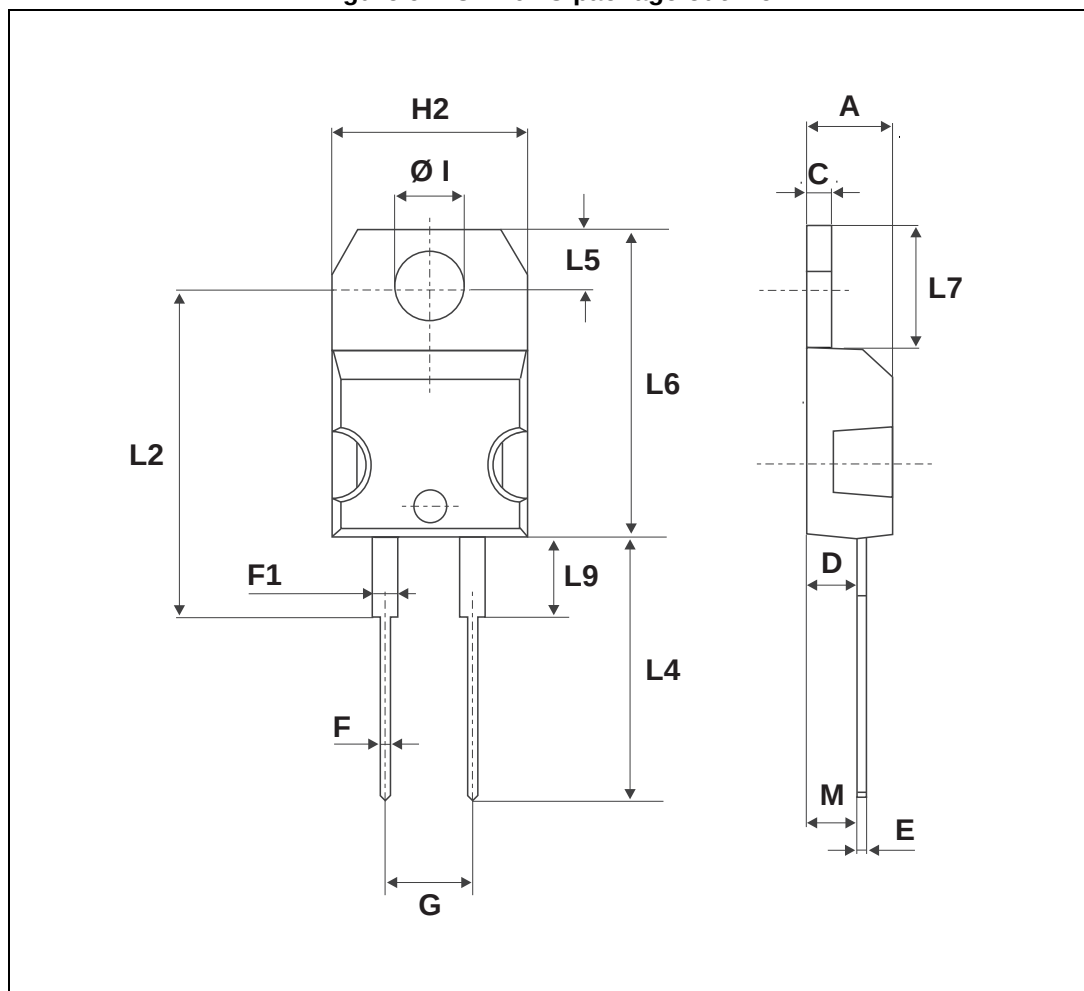


Table 6. TO-220AC package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPSC12H065D	PSC12H065D	TO-220AC	1.86 g	50	Tube

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
27-Nov-2014	1	First issue.
13-Jul-2015	2	Removed D ² PAK package information and updated Table 7 .

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